AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1-6. (Canceled)

7. (Currently Amended) A process of producing a web-form laminated material used for packaging containers comprising at least a support layer and a thermoplastic innermost layer, which includes,

providing a plurality of material rolls for the support layer,

delivering web-form support layers successively from the material rolls, printing a conductive layer of a conductive composition containing a metal conductive filler to the inner surface of the support layer directly or indirectly only at zones where heat-sealing is conducted by high-frequency induction heating for forming ~~the~~ a container,

printing a container design indirectly or directly to the outer surface of the web-form support layer,

forming identical or different ~~kind~~ kinds of single or multiple thermoplastic layers simultaneously or successively to the printed outer surface and inner surface of the web-form support layer, and then joining the top end of the web-form support layer at the upstream with the rear end of the web-form support layer at the downstream thereby forming a longer web-form support layer.

8-11. (Canceled)

12. (New) The process according to Claim 7, wherein the metal conductive filler comprises aluminum.

13. (New) The process according to Claim 7, wherein the metal conductive filler comprises silver.

14. (New) The process according to Claim 7, wherein the metal conductive filler comprises a metal powder or metal flake.

15. (New) The process according to Claim 7, wherein the shape of the conductive material is at least one of dendritic, scaly and flaky.

16. (New) The process according to Claim 7, wherein a content of the conductive composition in the conductive layer of constitutes 5 to 95% by weight of the conductive layer.

17. (New) The process according to Claim 7, wherein a content of the conductive composition in the conductive layer of constitutes 60 to 90% by weight of the conductive layer.